

# **Advance Product Change Notification**

Issue Date: 27-Apr-2015

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# 201504012A



#### **Management Summary**

Enable ASEN as a second source assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types

### **Change Category**

[] Wafer Fab process	[] Assembly Process	[] Product Marking	[] Design

[] Wafer Fab materials [] Assembly Materials [] Electrical spec./Test coverage [] Mechanical Specification [] Wafer Fab location [X] Assembly Location [X] Test Location [] Packing/Shipping/Labeling

PL-HSI & MCU HVQFN32/HVQFN48 ASEN second source assembly & test

### **Details of this Planned Change**

- Enable ASEN as an assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types.
- Assembly Material types and Test platforms will be the same
- NXP APK (the parent factory) provided loadboards for ATE use,

# Why do we Plan this Change

- The purpose is to expand our production capacity and to increase planning flexibility

### **Identification of Affected Products**

Top side marking

Top side marking with different marking code for new assembly center.

The marking of the assembly center is setup in the 3rd row where "X" indicates the assembly center ASEN.

# **Product Availability**

#### Sample Information

Samples are available upon request

#### **Production**

Planned first shipment 17-Jul-2015

#### **Impact**

no impact to the product's functionality anticipated.

No material changes or test platform changes will occur.

### **Disposition of Old Products**

Existing inventory will be shipped until depleted

# **Timing and Logistics**

The Self Qualification Report will be ready on 18-May-2015.

The Final PCN is planned to be issued on: 18-May-2015.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 27-May-2015.

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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PTN3360DBS,518	935291567518
LPC11U24FHI33/301,	935297186551
LPC11U35FHI33/501,	935297259551
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